

## 54ABT240

# Octal Buffer/Line Driver with TRI-STATE® Outputs

#### **General Description**

The 'ABT240 is an inverting octal buffer and line driver designed to be employed as a memory address driver, clock driver and bus oriented transmitter or receiver which provides improved PC board density.

- Guaranteed latchup protection
- High impedance glitch free bus loading during entire power up and power down cycle
- Nondestructive hot insertion capability
- Standard Microcircuit Drawing (SMD) 5962-9318801

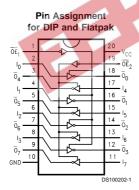
#### **Features**

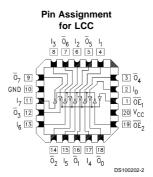
■ Output sink capability of 48 mA, source capability of 24 mA

#### **Ordering Code**

Military	Package Number	Package Description			
54ABT240J-QML	J20A	20-Lead Ceramic Dual-In-Line			
54ABT240W-QML	W20A	20-Lead Cerpack			
54ABT240E-QML	E20A	20-Lead Ceramic Leadless Chip Carrier, Type C			

### **Connection Diagrams**





Pin Names	Description				
$\overline{OE}_1$ , $\overline{OE}_2$	TRI-STATE Output				
	Enable Inputs				
$I_0 - I_7$	Inputs				
$\overline{O}_0 - \overline{O}_7$	Outputs				

TRI-STATE® is a registered trademark of National Semiconductor Corporation

#### **Truth Tables**

Inputs		Outputs		
ŌE₁	I <sub>n</sub>	(Pins 12, 14, 16, 18)		
L	L	Н		
L	Н	L		
Н	X	Z		

Inputs		Outputs		
ŌĒ₂	l <sub>n</sub>	(Pins 3, 5, 7, 9)		
L	L	Н		
L	Н	L		
Н	X	Z		

- H = HIGH Voltage Level
- L = LOW Voltage Level
  X = Immaterial
  Z = High Impedance



#### **Absolute Maximum Ratings** (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

 $\begin{array}{ll} \mbox{Storage Temperature} & -65\mbox{°C to } +150\mbox{°C} \\ \mbox{Ambient Temperature under Bias} & -55\mbox{°C to } +125\mbox{°C} \\ \end{array}$ 

Junction Temperature under Bias

Ceramic -55°C to +175°C

V<sub>CC</sub> Pin Potential to

 Ground Pin
 -0.5V to +7.0V

 Input Voltage (Note 2)
 -0.5V to +7.0V

 Input Current (Note 2)
 -30 mA to +5.0 mA

Voltage Applied to Any Output

in the Disabled or

Power-Off State  $$-0.5{\rm V}$ to 5.5{\rm V}$ in the HIGH State <math display="inline">$-0.5{\rm V}$ to ${\rm V}_{\rm CC}$$ 

Current Applied to Output

in LOW State (Max) twice the rated I<sub>OL</sub> (mA)

DC Latchup Source Current (Across Comm Operating Range)

Over Voltage Latchup (I/O)

–150 mA 10V

# Recommended Operating Conditions

Free Air Ambient Temperature

Military –55°C to +125°C

Supply Voltage

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

 $\textbf{Note 2:} \ \ \textbf{Either voltage limit or current limit is sufficient to protect inputs.}$ 

#### **DC Electrical Characteristics**

Symbol	Parar	neter	ABT240		Units	V <sub>CC</sub>	Conditions		
			Min	Тур	Max	- 75	-		
V <sub>IH</sub>	Input HIGH Voltage		2.0		N. C.	V	717	Recognized HIGH Signal	
V <sub>IL</sub>	Input LOW Voltage				0.8	V	0.	Recognized LOW Signal	
V <sub>CD</sub>	Input Clamp Diode Volta	ige	. 1		-1.2	V	Min	I <sub>IN</sub> = -18 mA	
V <sub>OH</sub>	Output HIGH Voltage	54ABT	2.5			V	Min	I <sub>OH</sub> = -3 mA	
		54ABT	2.0			V	Min	I <sub>OH</sub> = -24 mA	
V <sub>OL</sub>	Output LOW Voltage	54ABT	$\angle$		0.55	V	Min	I <sub>OL</sub> = 48 mA	
I <sub>IH</sub>	Input HIGH Current				5	μA	Max	V <sub>IN</sub> = 2.7V (Note 4)	
			1		5			V <sub>IN</sub> = V <sub>CC</sub>	
I <sub>BVI</sub>	Input HIGH Current Brea	akdown Test			7	μA	Max	V <sub>IN</sub> = 7.0V	
I <sub>IL</sub>	Input LOW Current				-5	μA	Max	V <sub>IN</sub> = 0.5V (Note 4)	
					-5			V <sub>IN</sub> = 0.0V	
V <sub>ID</sub>	Input Leakage Test		4.75			V	0.0	I <sub>ID</sub> = 1.9 μA	
								All Other Pins Grounded	
I <sub>OZH</sub>	Output Leakage Current				50	μΑ	0 - 5.5V	V <sub>OUT</sub> = 2.7V; <del>OE</del> <sub>n</sub> = 2.0V	
I <sub>OZL</sub>	Output Leakage Current				-50	μΑ	0 - 5.5V	$V_{OUT} = 0.5V; \overline{OE}_n = 2.0V$	
Ios	Output Short-Circuit Current		-100		-275	mA	Max	V <sub>OUT</sub> = 0.0V	
I <sub>CEX</sub>	Output High Leakage Current				50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>	
I <sub>ZZ</sub>	Bus Drainage Test				100	μA	0.0	V <sub>OUT</sub> = 5.5V; All Others GND	
I <sub>CCH</sub>	Power Supply Current				50	μA	Max	All Outputs HIGH	
I <sub>CCL</sub>	Power Supply Current				30	mA	Max	All Outputs LOW	
I <sub>CCZ</sub>	Power Supply Current				50	μA	Max	$\overline{OE}_n = V_{CC};$	
								All Others at V <sub>CC</sub> or Ground	
I <sub>CCT</sub>	Additional I <sub>CC</sub> /Input	Outputs Enabled			1.5	mA	Max	$V_I = V_{CC} - 2.1V$	
		Outputs TRI-STATE			1.5	mA		Enable Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V	
		Outputs TRI-STATE			50	μA		Data Input V <sub>I</sub> = V <sub>CC</sub> - 2.1V	
								All Others at V <sub>CC</sub> or Ground	
I <sub>CCD</sub>	Dynamic I <sub>CC</sub>	No Load				mA/	Max	Outputs Open	
	(Note 4)				0.1	MHz		$\overline{OE}_n$ = GND, (Note 3)	
								One Bit Toggling, 50% Duty Cycle	

Note 3: For 8 bits toggling, I<sub>CCD</sub> < 0.8 mA/MHz.

Note 4: Guaranteed, but not tested.

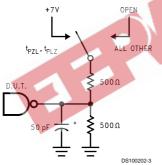
Symbol	DI Parameter 54ABT		ABT	Units	Fig. No.
		T <sub>A</sub> = -55°C to +125°C			
		V <sub>CC</sub> = 4	V <sub>CC</sub> = 4.5V-5.5V		
		C <sub>L</sub> =	50 pF		
		Min	Max		
t <sub>PLH</sub>	Propagation Delay	0.8	5.5	ns	Figure 5
t <sub>PHL</sub>	Data to Outputs	1.0	5.5		
t <sub>PZH</sub>	Output Enable	0.8	7.5	ns	Figure 4
$t_{PZL}$	Time	0.8	7.7		
t <sub>PHZ</sub>	Output Disable	1.0	7.5	ns	Figure 4
t <sub>PLZ</sub>	Time	1.0	7.2		

# Capacitance

Symbol	Parameter	Тур	Units	Conditions T <sub>A</sub> = 25°C
C <sub>IN</sub>	Input Capacitance	5.0	pF	V <sub>CC</sub> = 0V
C <sub>OUT</sub> (Note 5)	Output Capacitance	9.0	pF	V <sub>CC</sub> = 5.0V

Note 5: C<sub>OUT</sub> is measured at frequency f = 1 MHz, per MIL-STD-883B, Method 3012.

AC Loading



Amplitude Rep. Rate 3.0V 1 MHz 500 ns 2.5 ns 2.5 ns

FIGURE 3. Test Input Signal Requirements

\*Includes jig and probe capacitance

FIGURE 1. Standard AC Test Load

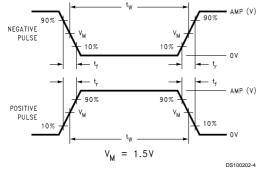
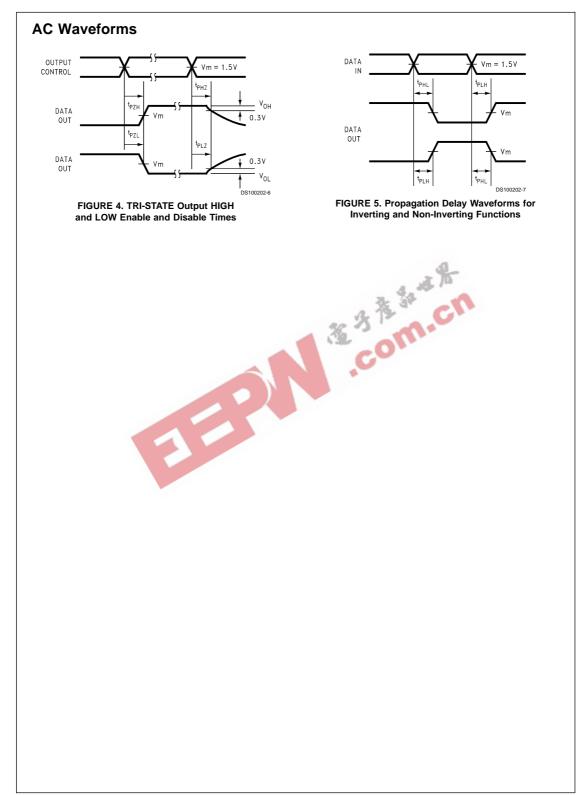
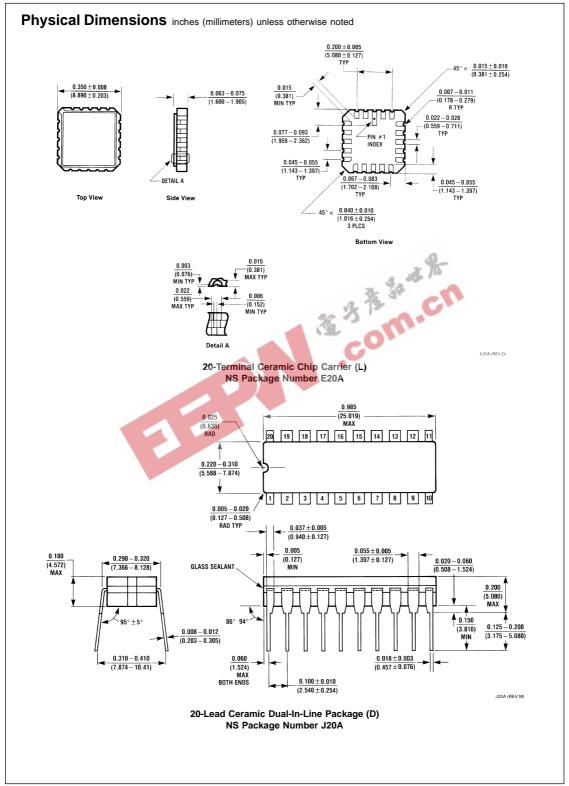


FIGURE 2. Test Input Signal Levels

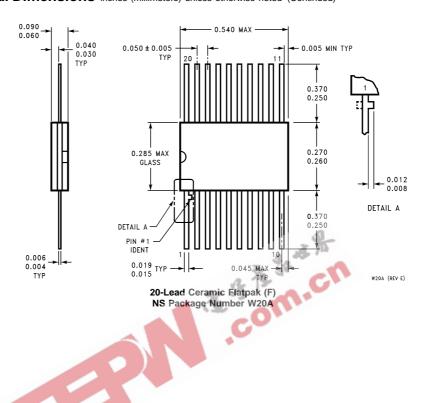






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#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



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